RENESAS

PHOTO DIODE NDL5521P Series

2.5 Gb/s OPTICAL FIBER COMMUNICATIONS ϕ 50 μm InGaAs AVALANCHE PHOTO DIODE WITH MMF

DESCRIPTION

NDL5521P Series are InGaAs avalanche photo diode modules with multimode fiber. They are designed for 2.5 Gb/s optical fiber communication systems and cover the wavelength range between 1 000 and 1 600 nm with high efficiency.

These modules are also available with FC-PC connector and SC-PC connector.

FEATURES

- Small dark current
 ID = 5 nA
- High quantum efficiency
- η = 90 % @ λ = 1 300 nm, M = 1

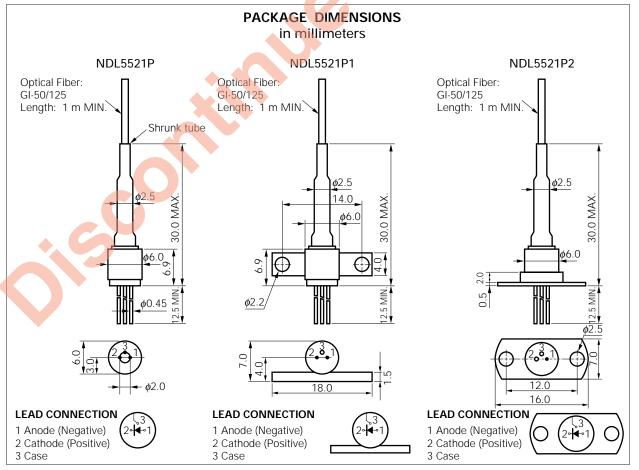
*φ*50 μm

High speed response

fc = 2.5 GHz MIN. @M = 10

 $\eta = 77 \% @ \lambda = 1550 \text{ nm}, \text{ M} = 1$

- Detecting area size
- · Coaxial module with multimode fiber (GI-50/125)
- NDL5521P1 and NDL5521P2 have a flange.



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ORDERING INFORMATION

| PART NUMBER | AVAILABLE CONNECTOR |
|-------------|----------------------|
| NDL5521P | Without Connector |
| NDL5521PC | With FC-PC Connector |
| NDL5521PD | With SC-PC Connector |
| NDL5521P1 | Without Connector |
| NDL5521P1C | With FC-PC Connector |
| NDL5521P1D | With SC-PC Connector |
| NDL5521P2 | Without Connector |
| NDL5521P2C | With FC-PC Connector |
| NDL5521P2D | With SC-PC Connector |

ABSOLUTE MAXIMUM RATINGS (Tc = 25 °C)

| Forward Current | IF | 10 | mA |
|----------------------------|------|------------|----|
| Reverse Current | Ir | 0.5 | mA |
| Operating Case Temperature | Tc | -40 to +85 | °C |
| Storage Temperature | Tstg | -40 to +85 | °C |

ELECTRO-OPTICAL CHARACTERISTICS (Tc = 25 °C)

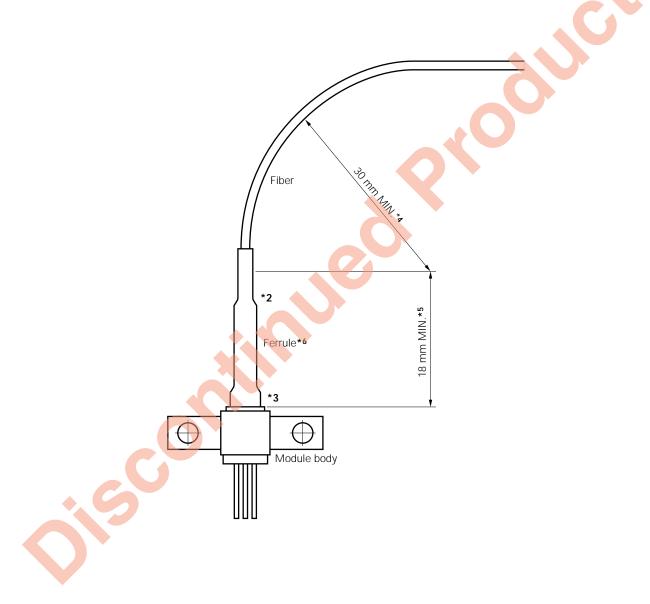
| CHARACTERISTIC | SYMBOL | MIN. | TYP. | MAX. | UNIT | TEST CONDITIONS |
|---|--------------------|------|------|------|------|---|
| Reverse Breakdown Voltage | V _{(BR)R} | 40 | 55 | 80 | V | $I_D = 100 \ \mu A$ |
| Temperature Coefficient of Reverse Breakdown Voltage | δ*1 | | 0.2 | | %/°C | |
| Dark Current | lo | | 5 | 30 | nA | $V_R = V_{(BR)R} \times 0.9$ |
| Multiplied Dark Current | Ірм | | 0.5 | 5 | nA | M = 2 to 10 |
| Terminal Capacitance | Ct | | 0.4 | 0.75 | pF | $V_{\text{R}} = V_{(\text{BR})\text{R}} \times 0.9, \ f = 1 \ MHz$ |
| Cut-off Frequency | | 2.5 | | | GHz | M = 5 |
| | fc | 2.5 | 3.0 | | | M = 10 |
| | | 1.0 | | | | M = 30 |
| Quantum Efficiency | η | 76 | 90 | | % | λ = 1 300 nm, M = 1 |
| | | 65 | 77 | | | λ = 1 550 nm, M = 1 |
| Responsivity | S | 0.8 | 0.94 | | A/W | λ = 1 300 nm, M = 1 |
| | | 0.81 | 0.96 | | | λ = 1 550 nm, M = 1 |
| Multiplication Factor | Μ | 30 | 40 | | | $\lambda = 1550 \text{ nm}, \text{ Ipo} = 1.0 \ \mu\text{A}$ V _R = V (@ I _D = 1 \ \mu\text{A}) |
| Excess Noise Factor | х | | 0.7 | | | λ = 1 300 nm, 1 550 nm, I _{po} = 1.0 μ A |
| Excess Noise Coefficient | F | | 5 | | | M = 10, f = 35 MHz, B = 1 MHz |
| Optical Return Loss | ORL | | 30 | | dB | |

 $*1: \delta = \frac{V_{(\text{BR})\text{R}} < 25 \text{ }^{\circ}\text{C} + \Delta\text{T} \text{ }^{\circ}\text{C} > - V_{(\text{BR})\text{R}} < 25 \text{ }^{\circ}\text{C} >}{\Delta\text{T} \text{ }^{\circ}\text{C} \cdot V_{(\text{BR})\text{R}} < 25 \text{ }^{\circ}\text{C} >}$

HANDLING PRECAUTION for NEW TYPE PD/APD MODULE

The NEC's new type PD/APD module has the shrunk tube to guard the ferrule edge^{*2} and the junction between the ferrule and the module body^{*3}. If adequate care is not taken with the shrunk tube module, there is possibility of fiber-break and/or optical coupling degradation. In order to protect this module, NEC recommends following condition for handling.

- 1. Keep the minimum fiber bend radius (30 mm min.*⁴).
- 2. Do not bend the fiber within the 18 mm region $^{\rm +5}$ from the module body.
- 3. Do not stress the ferrule *6, lateral force < 500 g.



InGaAs APD FAMILY

| FEATURES | | A | PD | | |
|--|------------------------------------|------------------------------------|--|--|---|
| PACKAGES | <i>φ</i> 30 μm | <i>φ</i> 50 μm (for 2.5G) | <i>φ</i> 50 μm | <i>φ</i> 80 μm | REMARKS |
| TO-18 CAN | NDL5530 | | NDL5500 | NDL5510 | 3PIN |
| CHIP ON CARRIER | NDL5530C | NDL5520C | NDL5500C | NDL5510C | |
| COAXIAL MODULE WITH MMF | | NDL5521P NDL5521P1 NDL5521P2 | NDL5551P NDL5551P1 NDL5551P2 NDL5553P*8 NDL5553P2*8 NDL5553P2*8 NDL5590P*9 NDL5590P1*9 NDL5590P1*9 | NDL5561P* ⁷ NDL5561P1* ⁷ NDL5561P2* ⁷ | P1, P2: WITH FLANGE |
| COAXIAL MODULE WITH SMF | NDL5531P NDL5531P1 NDL5531P2 | | | | 0 |
| 14 PIN DIP MODULE WITH TEC, MMF* ⁸ | | | NDL5506P NDL5506PS | NDL5516P*7 | ⊿T = 45 K (@lc = 1.1 A) PS: WITH SMF |
| | | | NDL5507P NDL5507PS | NDL5517P*7 | ∆T = 65 K (@lc = 1.3 A) PS: WITH SMF |
| 6 PIN BFY MODULE WITH MMF | | NDL5522P* ⁹ | | | |

*7 WITH GI62.5 *8 FOR OTDR APPLICATION *9 WITH PRE-AMP

REFERENCE

| le on NEC semiconductor devices IEI-1209 itor device mounting technology manual IEI-1207 itor device package manual IEI-1213 ality assurance for semiconductor devices IEI-1202 itor selection guide MF-1134 | Quality grade on NEC semiconductor devices IEI-1209 Semiconductor device mounting technology manual IEI-1207 Semiconductor device package manual IEI-1213 Guide to quality assurance for semiconductor devices IEI-1202 | NEC semiconductor device reliability/quality control system | Document No. |
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| tor device mounting technology manual IEI-1207 tor device package manual IEI-1213 ality assurance for semiconductor devices IEI-1202 tor selection guide MF-1134 | Semiconductor device mounting technology manual IEI-1207 Semiconductor device package manual IEI-1213 Guide to quality assurance for semiconductor devices IEI-1202 Semiconductor selection guide MF-1134 | We semiconductor device renability/quality control system | IEI-1205 |
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| tor selection guide MF-1134 | Semiconductor selection guide MF-1139 | Semiconductor device package manual | IEI-1213 |
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| | | Semiconductor selection guide | MF-1134 |
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CAUTION

Within this module there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstance break the hermetic seal.

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- Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
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Anti-radioactive design is not implemented in this product.

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